



K888G7



Intel® Xeon® 6 Processors- Based Server System

Highlights

- **Support dual Intel® Xeon® 6 processor with E-cores and P-cores, up to 176 PCIe lane from two CPUs**
- **Support DDR5 RDIMM, 6400 MT/s @ 1DPC, 5200 MT/s @ 2DPC**
- **Extremely scalable with up to PCIe Gen5 x16 DW FHFL GPU card x4**
- **Support up to 26 U.2 SSD**
- **Optional Liquid Cooling**

As AI models grow in complexity, and data-intensive applications such as high-performance computing (HPC), cloud infrastructure, and analytics continue to surge, data centers are under pressure to deliver more performance, flexibility, and efficiency than ever before. The Inventec K888G7 is purpose-built to meet these challenges. Equipped with dual Intel® Xeon® 6 processors featuring a hybrid architecture of Performance-cores (P-cores) and Efficient-cores (E-cores), the K888G7 delivers a new level of compute capability, adapting to diverse and dynamic workload requirements while optimizing power consumption and core utilization.

A Powerful, Scalable, and Flexible 2U Server

Designed to handle a wide range of data center applications from general-purpose computing to AI training and high-performance simulation, the Inventec K888G7 delivers the ideal balance of performance, memory bandwidth, and I/O scalability. Powered by dual Intel® Xeon® 6 processors, it supports up to 176 PCIe lanes across two CPUs, enabling high-throughput connectivity for GPU acceleration, high-speed networking, and large-scale storage.

The system features DDR5 RDIMM memory with speeds of up to 6400 MT/s at 1DPC and 5200 MT/s at 2DPC, ensuring responsive access to data in memory-intensive workloads. For compute-heavy tasks, the K888G7 accommodates up to four PCIe Gen5 x16 double-width FHFL GPU cards and supports up to 26 U.2 SSDs, providing the flexibility and performance required for AI inference, HPC, and data analytics environments.

Designed with Customer Needs

The Inventec K888G7 offers design flexibility that addresses both performance requirements and operational efficiency. To support diverse workload scenarios, it provides multiple thermal strategies, including both traditional forced-air cooling and optional liquid cooling. This gives customers the ability to optimize their systems for maximum performance or improved energy efficiency, depending on their data center goals such as throughput, PUE, or TCO.

In addition to cooling flexibility, the K888G7 supports remote management and monitoring through a baseboard management controller (BMC), ensuring real-time visibility into system health and operation. Furthermore, Inventec offers a customized software service to help customers tailor the monitoring experience to their unique deployment needs, providing a more adaptable and responsive server management solution.

About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

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Form Factor	2U 19" Rack Mount 850.0mm(D)x438.0/447.6mm(W)x87.0mm(H) (33.4 x17.2/17.6 x3.42 inch)
Processor	Intel® Xeon® 6700-series with E-cores Intel® Xeon® 6700/6500-series with P-cores
GPU Module	Support 4 x DW FHFL GPU card, TDP 350W NVIDIA L40/L40S/H100
Memory	32 xDDR5 DIMM (2DPC) Support DDR5 RDIMM 32GB/64GB/96GB/ 128GB, MCR DIMM 32GB/48GB/64GB RDIMM Support Speed : 6400 MT/s @ 1DPC, 5200 MT/s @ 2DPC MCR DIMM Support Speed : 8000 MT/s @ 1DPC
PCIe Gen5	88 PCIe lanes/Per CPU(56 lanes for North, 32 lanes for South), PCIe Bifurcation : x16, x8, x4, x2(Gen5) 64 CXL 2.0 lanes per CPU, CXL bifurcation : x16,x8, x4 Total 176 PCIe lanes
Storage/PCIe	Front : Up to 24 NVMe SSD, U.2 or E3.S form factor (40w max) Up to 12x 3.5" HDD or 12x U.2 Rear: Up to 2x3.5" HDD Up to 4x U.2/2.5 SATA HDD Up to 2x2 Slot PCIe Riser(HBA card) Up to 1x DW-FH AIC or (1xFHHL + OCP3.0) Internal: Support 2xPCIe/SATA M.2 (2280, 22110) (SATA or PCIe x2 lanes)
Networking	Support Rear OCP 3.0(2x100G) and Smart NIC card(DW)
BMC	AST2600 chipset with 1GB RAM
TPM	TPM 2.0
Power Supply	CRPS power supply support 100V-240V, 240V HVDC support 1+1 active-active Support hot plug
Fan	5+1 6056 Fan (dual motors)

Inventec Corporation (TAO)

No.88, Dazhi Rd., Taoyuan Dist., Taoyuan City 33068, Taiwan
Tel: 886-3-390-0000 Fax: 886-3-376-2370
Email: TAOproductsupport@inventec.com

Learn more at <https://ebg.inventec.com/>

